

C0805C103K2REC7210

ESD SMD Comm X7R, Ceramic, 0.01 uF, 10%, 200 VDC, X7R, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class II, 0805



Click here for the 3D model.

Dimensions	
Chip Size	0805
L	2mm +/-0.2mm
W	1.25mm +/-0.2mm
Т	0.78mm +/-0.10mm
S	0.75mm MIN
В	0.5mm +/-0.25mm

Packaging Specifications Packaging

Packaging Packaging Quantity T&R, 330mm, Paper Tape 15000

General Information	
Series	ESD SMD Comm X7R
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class II
Features	Temperature Stable, Class II
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Component Weight	11 mg
Shelf Life	78 Weeks
MSL	1

Specifications		
Capacitance	0.01 uF	
Measurement Condition	1 kHz 1.0Vrms	
Capacitance Tolerance	10%	
Voltage DC	200 VDC	
ESD Level per AEC-Q200	25,000 V ESD Level	
Dielectric Withstanding Voltage	500 VDC	
Temperature Range	-55/+125°C	
Temperature Coefficient	X7R	
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms	
Dissipation Factor	2.5%1kHz1.0Vrms	
Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours	
Insulation Resistance	100 GOhms	

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